MA2Z748

Silicon epitaxial planar type

For super high speed switching For small current rectification

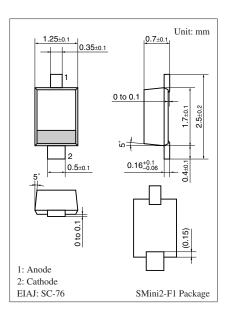
■ Features

- Low V_F type of MA3X720
- Low forward voltage V_F and good rectification efficiency
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V _R	20	V
Repetitive peak reverse voltage	V _{RRM}	20	V
Forward current (Average)	I _{F(AV)}	300	mA
Non-repetitive peak forward surge current *	I _{FSM}	3	A
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



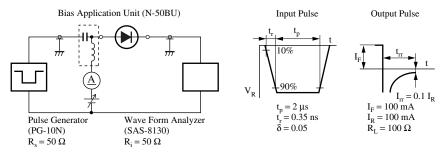
Marking Symbol: 2K

■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

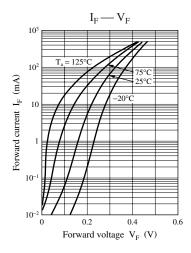
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F}	$I_F = 300 \text{ mA}$			0.4	V
Reverse current	I_R	$V_R = 10 \text{ V}$			30	μΑ
Terminal capacitance	C _t	$V_R = 0 V, f = 1 MHz$		60		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		5		ns
		$I_{rr} = 0.1 I_R, R_L = 100 \Omega$				

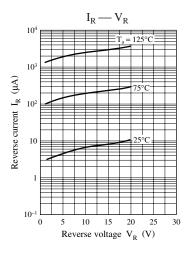
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

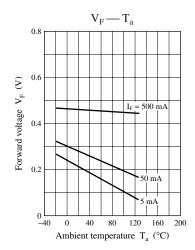
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 400 MHz.
- 4.*: t_{rr} measurement circuit

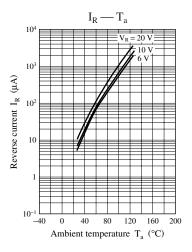


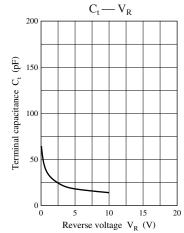
Panasonic

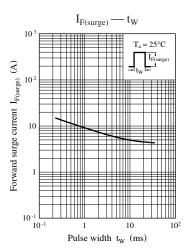












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